

ABSTRACT

A resin molded article having a reduced dielectric loss tangent is provided. This resin molded article is obtained by performing a heat treatment
5 to a resin composition comprising a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer at a temperature lower than a flow-beginning temperature of the liquid-crystalline polyester, preferably at a temperature between a lower limit temperature calculated by subtracting 120°C from the flow-beginning temperature and an upper limit temperature calculated
10 by subtracting 20°C from the flow-beginning temperature. This resin molded article has a smaller dielectric loss tangent than the resin molded article obtained from the resin composition without the heat treatment.